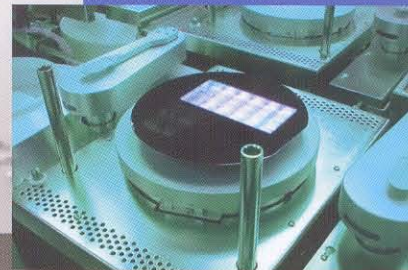


PHOTORESIST COATER SYSTEM



Mission Technology Inc. is a leading supplier of remanufactured and upgraded 86 and 86 series coater track systems. In addition to restoring the interior and exterior aspects of the system, we also enhanced the system with upgraded parts and/or modules, which have been tested rigorously in the field. Several examples of these components are listed below:

The SVG* 86 and 88 series photoresist coaters are fully automated systems, designed to uniformly coat wafers from 2" to 150mm. Both series of coater systems have been proven to process wafers with improved uniformity, repeatability, and speed.



LOW CONTACT CHUCKS provide better coating uniformity on wafers.

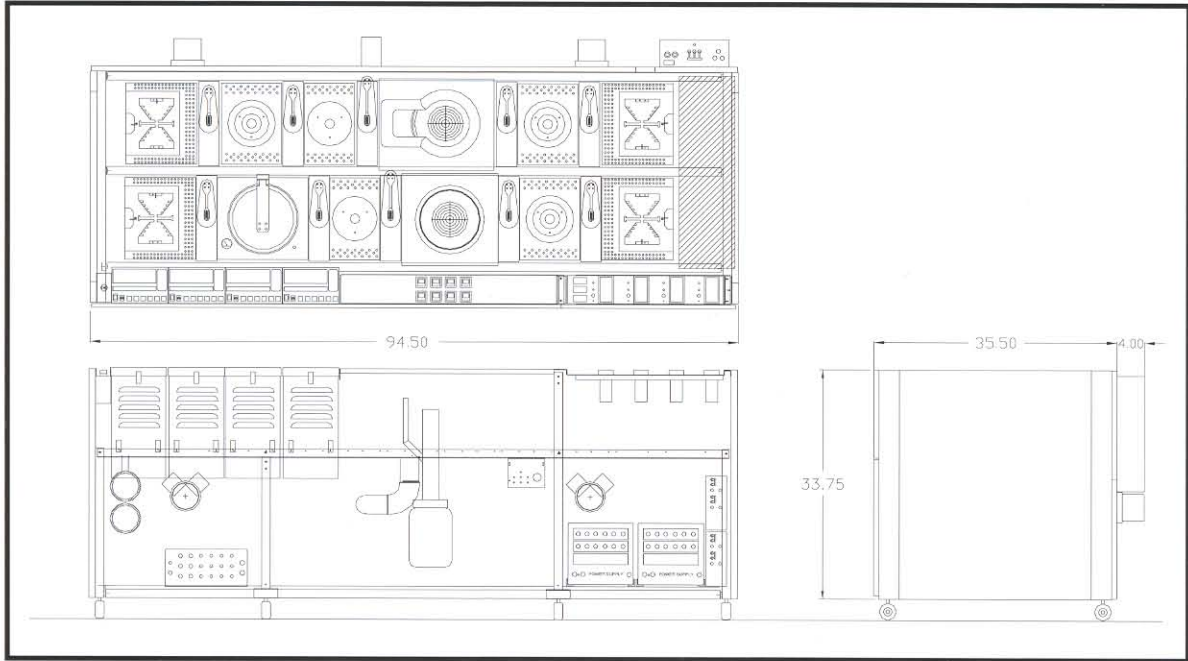
LOW PROFILE CATCH CUP assemblies are aerodynamically designed to carry mist away from the wafer, and have built-in bottom EBR to precisely remove edge beads and minimize chemical use.

BRUSHLESS SPINNER MOTORS have acceleration speeds of 50,000 rpm or better, and are virtually maintenance-free.

BOWL WASH or CCR assemblies clean the bowl surfaces, eliminating potential contamination-related problems.

VAPOR DISPENSE TIP BATHS keep dispense tips damp to prevent clogging and chemical crystallization, reducing particle generation.

UPGRADED HOT PLATE OVEN BLOCKS have optional features such as fixed proximity bake and Teflon-coated surface.



CONFIGURATION DRAWING SHOWN IN 88XX SERIES

CATEGORY	FEATURE	SPECIFICATION	FACILITY REQUIREMENTS	
SYSTEM BASIC	WAFER SIZE	3"-6" WAFERS (100MM - 150MM)	POWER	208 VAC, 3 PHASE, 15A (DIFFERENT VOLTAGE/PHASE COMBINATION POSSIBLE)
	USER INTERFACE / CONTROLLER	CARD CAGE		
VAPOR PRIME	TEMPERATURE RANGE	50 - 250°C ±0.5°C (50-150°C), ±0.5% (151-250°C)		
CHILL PLATE	TEMPERATURE RANGE	18.0 - 30°C ±0.1°C WITH CHILLER (IDLE AT AMBIENT)		
HPO	TEMPERATURE RANGE	50 - 250°C ±0.5°C (50-150°C), ±0.5% (151-250°C)	N ₂	80 PSI
COATER	MAXIMUM SPIN SPEED	6000 RPM (WITH 6" WF), 8500RPM (WITHOUT WF)	CDA	80 PSI
	ACCELERATION RANGE	0-50000RPM / SEC.	EXHAUST	2.5 INCH H ₂ O
	CHUCK TEMP. UNIFORMITY	±0.2°C ACROSS SPIN CHUCK	VACUUM	30 INCH HG
	DISPENSE	PROGRAMMABLE DISPENSE POSITION	DI WATER	25 PSI
	NUMBER OF NOZZLES	3 STANDARD NOZZLES (3/16")	PCW	17°C (± 2°C)
	RESIST TEMP. CONTROL	OPTIONAL ITEM		
	PREDISPENSE	YES		
	TOPSIDE EBR TYPE	ON P/R DISPENSE ARM		
	BOTTOMSIDE WASH	STANDARD		
	BOWL WASH TYPE	MULTI - HOLE CCR (OPTION)		
	SOLVENT NOZZLE TIP BATH	OPTION		
	AIR TEMP. CONTROL	±0.15°C (18-25°C RANGE), OPTION		
	HUMIDITY CONTROL	±1.0% (35.0-45.0% RH RANGE), OPTION		
WITHIN WAFER COATING UNIFORMITY	40Å (3µm) WITH P/R, AIR, HUMIDITY CONTROLLERS 60Å (3µm) WITHOUT P/R, AIR, HUMIDITY CONTROLLERS			
WAFER TO WAFER COATING UNIFORMITY	45Å (3µm) WITH P/R, AIR, HUMIDITY CONTROLLERS 65Å (3µm) WITHOUT P/R, AIR, HUMIDITY CONTROLLERS			
LONG TERM COATING STABILITY	55Å (3µm) WITH P/R, AIR, HUMIDITY CONTROLLERS 75Å (3µm) WITHOUT P/R, AIR, HUMIDITY CONTROLLERS			
RELIABILITY	MTBF	≥200 HOURS		
	MTBA	≥50 HOURS		
	MWBF	≥10,000 WAFERS		
	MWBA	≥2,000 WAFERS		
	UPTIME	≥95%		
	WAFER BREAKAGE	≤1 IN 10,000 WAFERS		
SAFETY	TEFLON WIRING	STANDARD		
	SOLVENT PLUMBING	TEFLON OR S.S.		
	SPILL CONTAINER IN CABINET	CUSTOM		
	EXHAUSTED CABINET	OPTION		

